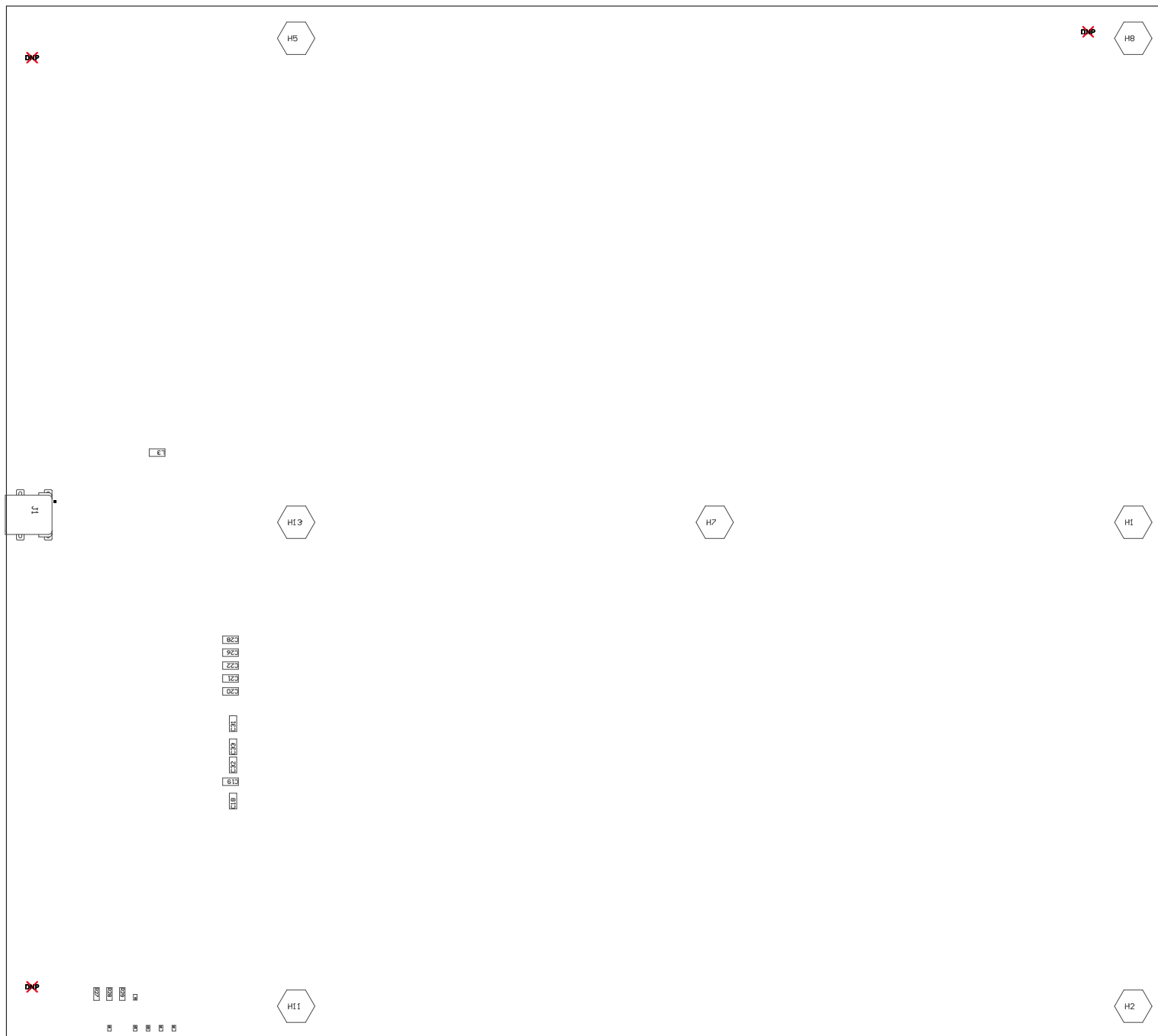


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

For evaluation only, not FCC approved for resale

- Z26 ■ Solder Pins 1, 2, 3, 18, 19, and 20 of U4 from the top to insure electrical continuity.
- Z26 ■ Solder U4 - B1 assembly to the board.
- Z26 ■ Slide pins of U4 into holes of B1. B1 must lie flat on the back of U4.
- Z26 ■ Remove protective coverings from B1 and U4
- Z26 ■ Component B1 must be assembled to U4 Before U4 is attached to the board.
- Z29 ■ Place SH-11 on J2, SH-12 on J3, SH-13 on J9 (pins 2-3), SH-14 on J5 (pins 1-2), and SH-15 on J5 (pins 5-6)
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z23 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

PCB VIEWED FROM TOP SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 10/14/2014 2:59:00 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: ISE4010	REV: E2	SUN REV: Not In VersionControl
	IGNORE ->		μI19v0 mottoB
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/14/2014 2:59:01 PM	TEXAS INSTRUMENTS	

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